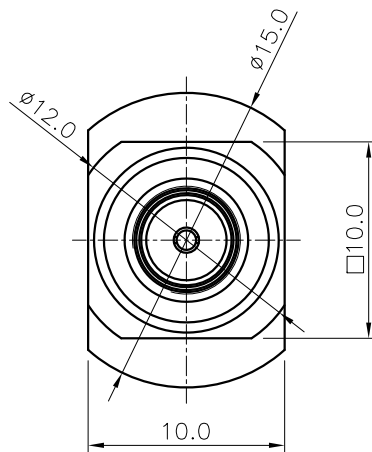
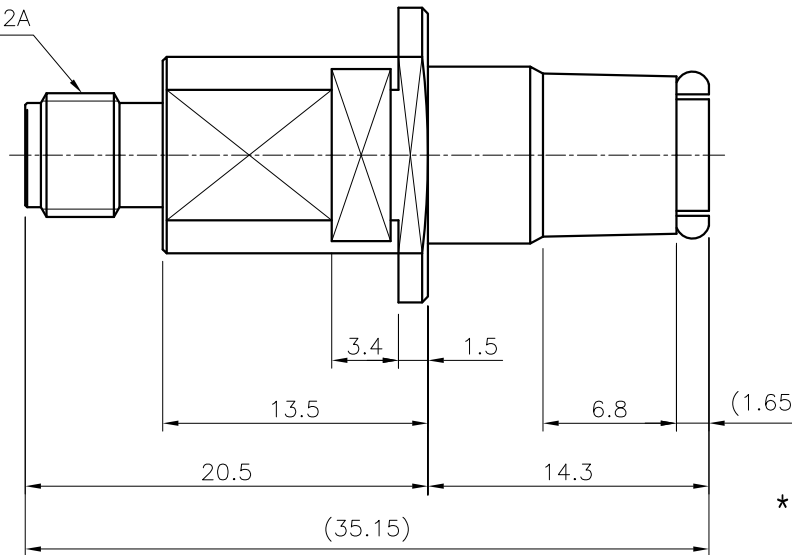


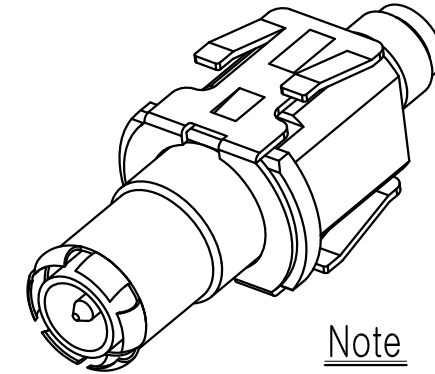
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	J.H.YOUN	2011.11.24.
1	설변(No.201604-0014)조립성 향상으로 TEFLON 공차 추가 및 변경, LOCK PANEL 코드 변경, 주기 추가	H.J.LEE	I.C.KIM	2016.04.29.
2	금형 노후화로 인해 바디 분리형으로 구조 변경	I.C.KIM		2021.09.08.



1/4-36 UNS-2A



VIEW A



Note

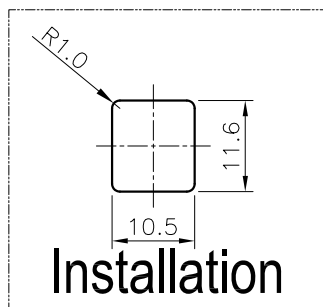
- * 조립 순서
- 1. JACK 조립
- 2. ④절연체 조립
- 3. ② PIN 조립
- 4. ⑤절연체 조립

* 내전압 검사 할 것

* PCB 두께 권장 사양 : 3.2t ±0.1mm

1	7	LOCK PANEL	1	SUS	Passivated	DSR00070-N/2
	6	JACK	1	BeCu C17300	Nickel Plate	DJA00039-5/1
1	5	INSULATOR	1	TEFLON		DIN01960-N/1
	4	INSULATOR	1	TEFLON		DIN01959-N/1
	3	CONTACT	1	BeCu C17300	Gold Plate	DAC00229-5/1
2	2	BODY	1	MBsBD C3604BD-F	Nickel Plate	DBD04776-5/1
2	1	BODY	1	ZnDC	Nickel Plate	DAD00084-5/4
						DAD00084-5/2
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2021. 09. 08.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle ±1°	APPROVED BY			
MATERIAL _____	CHECKED BY				TITLE SMA50 (J) TRU50 (P) ADAPTOR
	DRAWN BY	I.C.KIM			
FINISH _____	SCALE 2.5/1	UNIT mm		A4	DWG NO. AD00165-7/3
					REVISION 2



Installation